

LOW VOLTAGE TRANSIL™

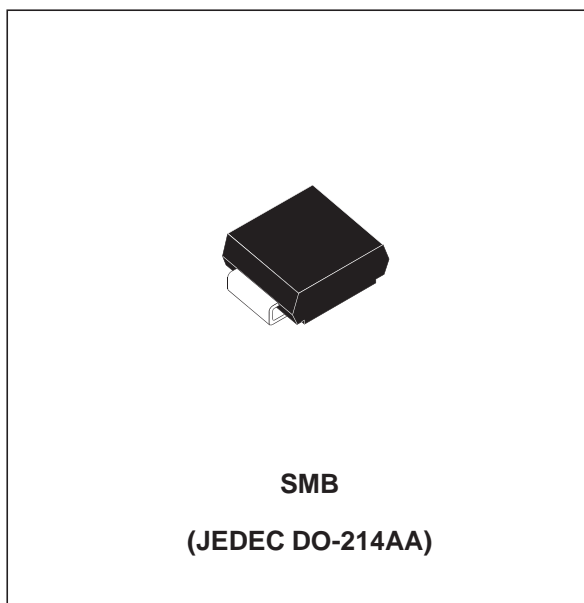
FEATURES

- UNIDIRECTIONAL TRANSIL DIODE
- PEAK PULSE POWER : 600 W (10/1000μs)
- REVERSE STAND-OFF VOLTAGE = 3.3 V
- LOW CLAMPING FACTOR
- FAST RESPONSE TIME
- UL RECOGNIZED

DESCRIPTION

The SMLVT3V3 is a Transil diode designed specifically for protecting 3.3V supplied sensitive equipment against transient overvoltages.

Transil diodes provide high overvoltage protection by clamping action. Their instantaneous response to transient overvoltages makes them particularly suited to protect voltage sensitive devices such as MOS technology and low voltage supply IC's.



ABSOLUTE MAXIMUM RATINGS (T_{amb} = 25°C)

Symbol	Parameter		Value	Unit
P _{PP}	Peak pulse power dissipation (see note 1)	T _j initial = T _{amb}	600	W
P	Power dissipation on infinite heatsink	T _{amb} = 75°C	5	W
I _{FSM}	Non repetitive surge peak forward current	t _p = 10 ms T _j initial = T _{amb}	50	A
T _{stg} T _j	Storage temperature range Maximum junction temperature		- 65 to + 175 175	°C °C
T _L	Maximum lead temperature for soldering during 10 s		260	°C

Note 1 : For a surge greater than the maximum values, the diode will fail in short-circuit.

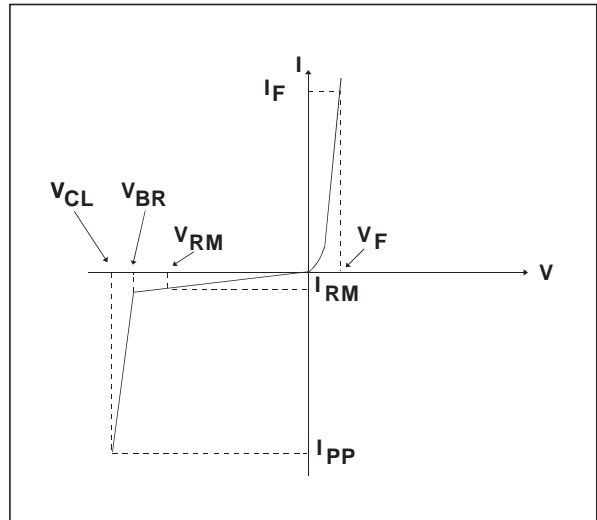
THERMAL RESISTANCE

Symbol	Parameter	Value	Unit
R _{th (j-l)}	Junction to leads	20	°C/W
R _{th (j-a)}	Junction to ambient on printed circuit on recommended pad layout	100	°C/W

SMLVT3V3

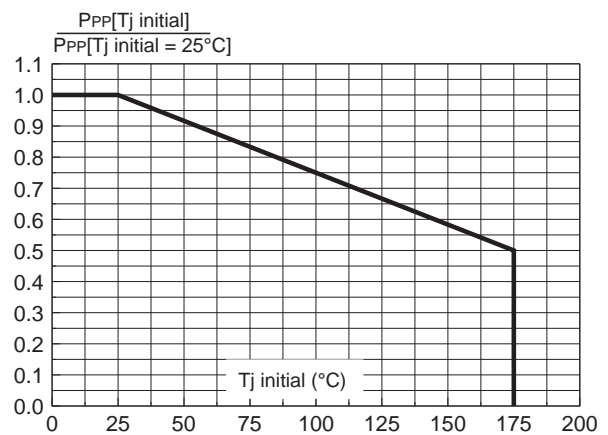
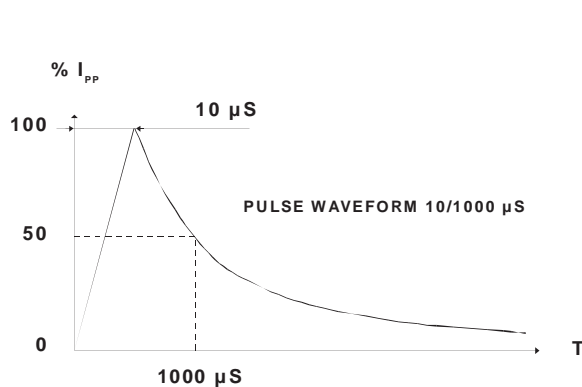
ELECTRICAL CHARACTERISTICS (T_{amb} = 25°C)

Symbol	Parameter
V _{RM}	Stand-off voltage.
V _{BR}	Breakdown voltage.
V _{CL}	Clamping voltage.
I _{RM}	Leakage current @ V _{RM} .
I _{PP}	Peak pulse current.
αT	Voltage temperature coefficient
V _F	Forward voltage drop



Type	I _{RM} @ V _{RM}		V _{BR} @ I _R		V _{CL} @ I _{PP}		V _{CL} @ I _{PP}		αT	C
	max		min		max		max		max	max
	μA	V	V	mA	V	A	V	A	10 ⁻⁴ /°C	pF
SMLVT3V3	200	3.3	4.1	1	7.3	50	10.3	200	-5.3	5200

Fig. 1 : Peak pulse power dissipation versus initial junction temperature (printed circuit board).



Note 2 : Pulse test : t_p < 50 ms

Note 3 : ΔV_{BR} = αT * (T_{amb} - 25) * V_{BR}(25°C).

Note 4 : V_R = 0V , F = 1MHz.

Fig. 2 : Peak pulse power versus exponential pulse duration (T_j initial = 25°C).

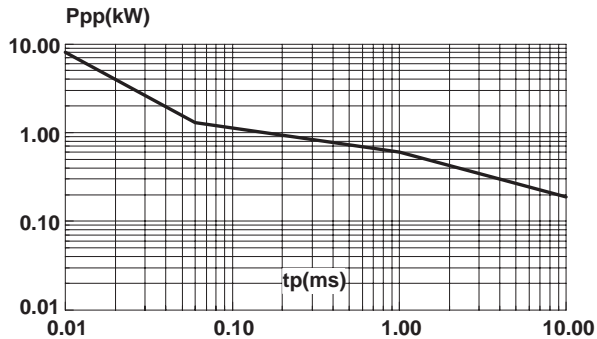


Fig. 3 : Clamping voltage versus peak pulse current (T_j initial = 25°C). Exponential waveform $t_p = 20 \mu s$ and $t_p = 1 ms$.

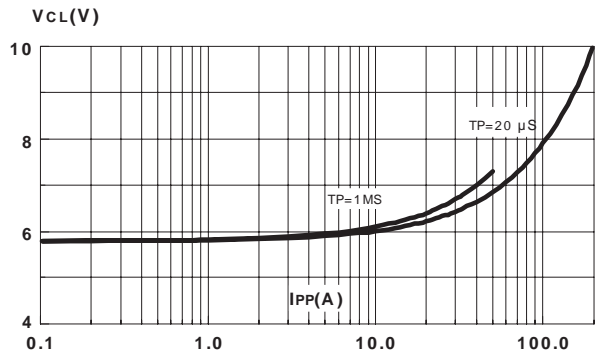


Fig. 4 : Capacitance versus reverse applied voltage (typical values).

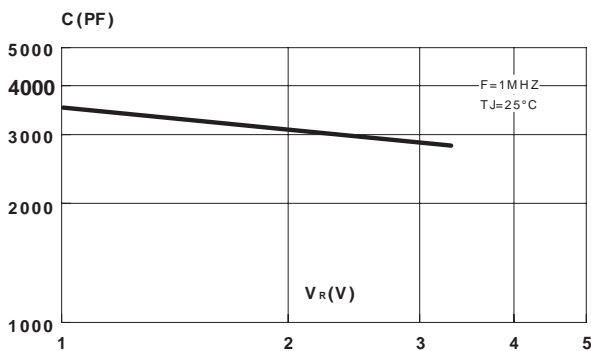


Fig. 5 : Peak forward voltage drop versus peak forward current (typical values).

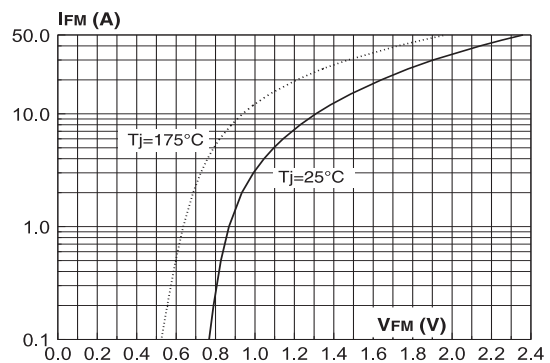


Fig. 6 : Transient thermal impedance junction ambient versus pulse duration. Mounting on FR4 PC Board with Recommended pad layout.

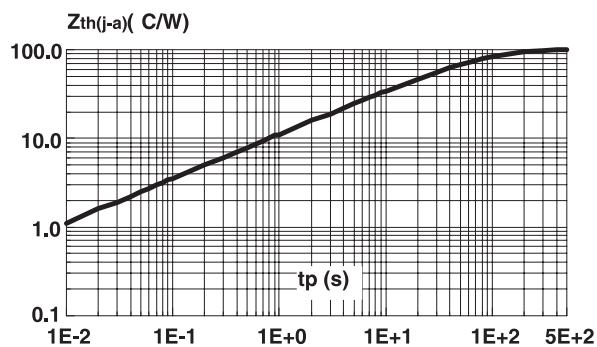
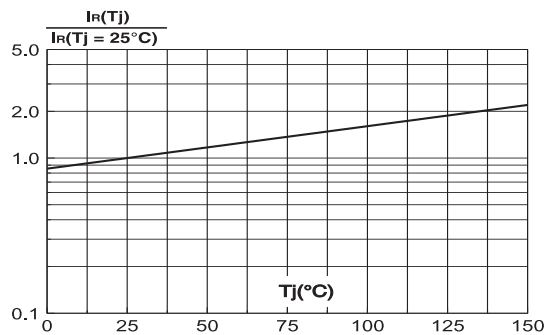
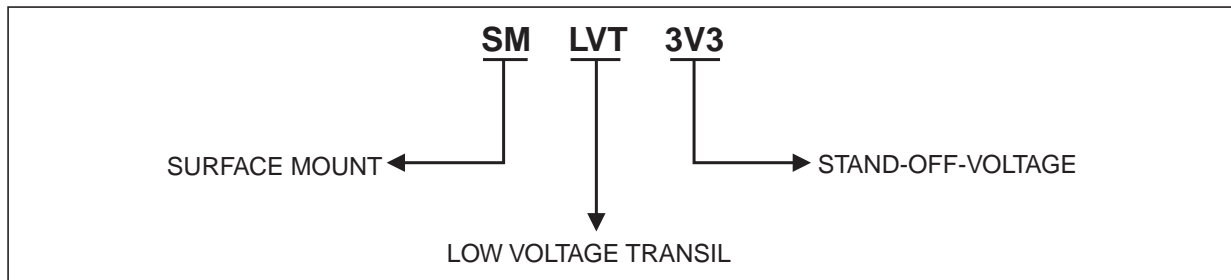


Fig. 7 : Relative variation of leakage current versus junction temperature.



SMLVT3V3

ORDER CODE



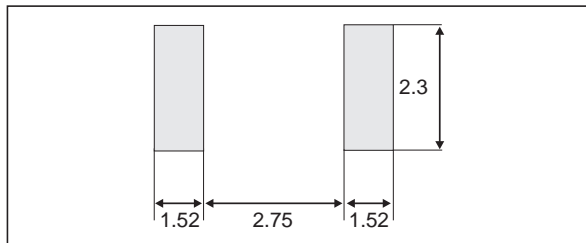
PACKAGE MECHANICAL DATA

SMB (Plastic) - Jedec DO-214AA

REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A1	1.90	2.15	2.45	0.075	0.085	0.096
A2	0.05	0.15	0.20	0.002	0.006	0.008
b	1.95		2.20	0.077		0.087
c	0.15		0.41	0.006		0.016
E	5.10	5.40	5.60	0.201	0.213	0.220
E1	4.05	4.30	4.60	0.159	0.169	0.181
D	3.30	3.60	3.95	0.130	0.142	0.156
L	0.75	1.15	1.60	0.030	0.045	0.063

FOOTPRINT DIMENSIONS (Millimeter)

SMB Plastic.



Marking: Logo, data code, type code and cathod band

Weight = 0.12 g

Packaging : standard packaging is in tape and reel.

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